

New Product: Welco® LED100 T7 SAC305 No-Clean Printing Paste

Welco® LED100 T7 SAC305 is a state-of-the-art no-clean printing paste, engineered primarily for miniLED and microLED attach applications. Paste release performance is exceptional at 70um stencil openings and highly consistent over its stencil life. LED100 series uses only Heraeus proprietary Welco® Type 7 powders to achieve highly reliable solder joints with low voids for customers' applications.

Welco® LED100 Benefits

- Uses high-quality Welco® T7 SAC305 powders
- Halogen-free and No-clean chemistry
- Best-in-class low-void performance
- Minimal solder beading
- Consistent fine pitch paste release
- Long stencil life (≥10hr) & staging life (≥10hr)
- Proven reliability and shear strength in miniLED application



Application Process

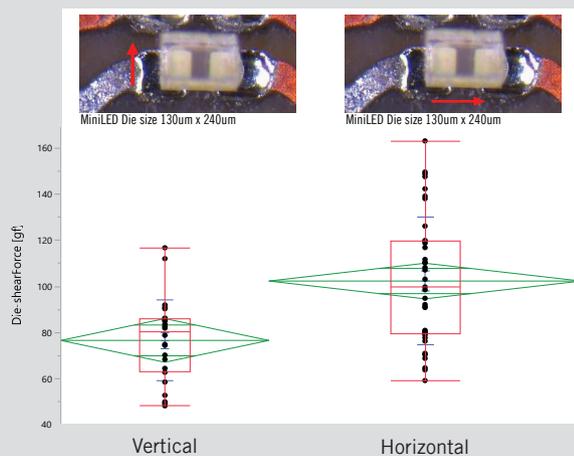


Suitable for both miniLED die attach, and SIP flip chip & component attach processes

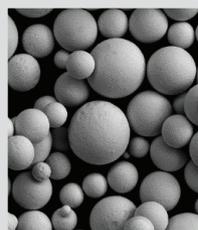
Staging Life Test - 12 hours	0 hr	4 hr	8 hr	12 hr
Low void performance (<10%) 008004 component post reflow x-ray inspection				

Stencil Life Test 12 hours continuous printing	0 hr	4 hr	8 hr	12 hr
<p>Consistent fine pitch paste release</p> <p>70um Stencil Opening</p> <p>50um line spacing</p> <p>ENIG substrate</p>				

MiniLED Die Shear Strength



Product Properties



High-quality Welco® T7 powders

- Narrow size distribution
- Uniform spherical shapes
- Batch-to-batch consistency

Physical Properties	LED100
Alloy	Sn/Ag3/Cu0.5
Powder Type	Welco® Type 7
Halogen Content	Halogen free
Flux Classification	No-Clean / Solvent Clean
Particle Size	2 - 11 µm
Melting Point	217 - 219 °C
Applications	Printing

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